



晶片鋁墊與打線腳位對應表

Pad Location Information

<i>Product Description</i>	
<i>Device Name</i>	__GDS6606CP5__
<i>Mask ID</i>	__BK2046A*__ (*代表 A-Z 共用版本,僅適用在 Pad 位置相同)
<i>Requirement</i>	<input type="checkbox"/> Tapeout 前 try bonding(封裝廠僅評估能否拉線) <input checked="" type="checkbox"/> Tapeout 後 ENG bonding diagram(封裝廠須出 BD 圖)
<i>Package Type & Size</i>	Package Type: CPC - 16 L *(<input type="checkbox"/> x <input type="checkbox"/> x <input type="checkbox"/> 膠體厚度) *L/F Pin Pitch: <input type="checkbox"/>
<i>Material type</i>	L/F Pad Size: <input type="checkbox"/> x <input type="checkbox"/> (SOP / TSOP / TSSOP / MSOP: <input type="checkbox"/> Normal <input checked="" type="checkbox"/> Exposed) Compound: Green
<i>Die Size</i>	<input type="checkbox"/> 1490 μm x <input type="checkbox"/> 1520 μm (Scribe Line: <input type="checkbox"/> 60 μm)
<i>Wafer Size</i>	<input type="checkbox"/> 8 Inch
<i>Material Description</i>	
<i>Wafer Substrate</i>	<input checked="" type="checkbox"/> P-Sub <input type="checkbox"/> N-Sub
<i>Die Bond Material</i>	<input checked="" type="checkbox"/> Conductive <input type="checkbox"/> Non-conductive <input type="checkbox"/> Other:
<i>Wire</i>	<input type="checkbox"/> Au 1.0mil <input type="checkbox"/> Cu 1.0mil <input checked="" type="checkbox"/> Other: _Cu 0.8_mil (備註:)
<i>Metal Layer</i>	Total <input type="checkbox"/> 4 layer, Top metal thickness: <input type="checkbox"/> 3.2(ThinM4/M3/M2)_ μm
<i>Circuit under bond pad</i>	<input type="checkbox"/> No <input checked="" type="checkbox"/> Yes
<i>Foundry</i>	FAB: SKHynix
<i>Metallization</i>	Al <input type="checkbox"/> 98% & Cu <input type="checkbox"/> 1.5% & Si <input type="checkbox"/> 0.5%
<i>Specially Bonding Note</i>	

Unit : μm

Bond Pad Name	Ball Center (X,Y)	Pad Center (X,Y)	Pad Size (X,Y)	L/F Pin Out Number	Bond Pad Name	Ball Center (X,Y)	Pad Center (X,Y)	Pad Size (X,Y)	L/F Pin Out Number
SUA		(-212.6,540.7)	(70,70)	1	ISPC		(436.5,-681.3)	(70,70)	9
		(-212.6,399)	(70,70)	NC	DNC		(666.3,-654.3)	(70,70)	10
		(-213.2,269.2)	(70,70)	NC	DPC		(664.3,-196.8)	(70,70)	11
GND		(-213.2,130.4)	(70,70)	1	CC2		(664.3,-37.1)	(70,70)	12
VDD		(-242.5,-239.3)	(70,70)	4	CC1		(664.3,168.5)	(70,70)	13
FBO		(-215.6,-418.6)	(70,70)	5	VBUSC		(657.5,677.4)	(70,70)	14
MPC		(-239.6,-681.3)	(70,70)	D/B 1	SRCGC		(537.1,677.4)	(70,70)	15
		(-34.5,-681.3)	(70,70)	NC	VBUS		(416.8,677.4)	(70,70)	1
		(159,-681.3)	(70,70)	NC			(264.5,682.3)	(70,70)	NC



ISMC	(298.8,-681.3)	(70,70)	8			(-212.6,682.3)	(70,70)	NC

Bond Pad LAYOUT of Chip

附件一

Brief 打線示意圖

附件二

